



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20170104002
Datasheet for LM2991
Information Only**

Date: January 09, 2017
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM2991S/NOPB	null
LM2991SX/NOPB	null
LM2991T/LF03	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20170104002	PCN Date:	1/9/2017
Title:	Datasheet for LM2991		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



LM2991

SNVS099I –MAY 1999 –REVISED OCTOBER 2016

Changes from Revision H (June 2013) to Revision I

Page

- Added Device Information and ESD Rating tables, Feature Description, Device Functional Modes, Application and Implementation, Power Supply Recommendations, Layout, Device and Documentation Support, and Mechanical, Packaging, and Orderable Information sections; moved some curves to Application Curves section 1
- Changed footnote 4 of Abs Max table and footnote 1 to Typical Characteristics to eliminate obsolete thermal values for thetaJA; updated values are in Thermal Information 4
- Changed Figure 14 as previous thermal values have been updated 8

The datasheet number will be changing.

Device Family	Change From:	Change To:
LM2991	SNVS099H	SNVS099I

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LM2991>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

LM2991S	LM2991S/NOPB	LM2991SX	LM2991SX/NOPB
LM2991T	LM2991T/LB03	LM2991T/LF03	LM2991T/NOPB

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com